

650V N-Channel Planar MOSFET

MOSFET

Metal Oxide Semiconductor Field Effect Transistor

650V N-Channel Planar MOSFET

650V N-Channel Planar MOSFET Power Transistor

DD65N04Ax Data Sheet

Rev. 2024 V1.0





650V N-Channel Planar MOSFET

Description

650V N-Channel Planar MOSFET

DD65N04Ax is HRM high voltage MOSFET family based on advanced planar stripe DMOS technology. This advanced MOSFET family has optimized on-state resistance, and also provides superior switching performance and higher avalanche energy strength. This device family is suitable for high efficiency switch mode power supplies.

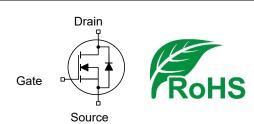
Features

- RDSON=2.7Ω @Vgs=10V, Id=2A
- Low gate Charge(typical 12.6nC)
- Low Crss (typical 1.3pF)
- Fast switching capability
- 100% avalanche tested
- Improved dv/dt capability
- ●RoHS compliant

TO-220F TO-252

Applications

- Switch Mode Power Supply
- Uninterruptible Power Supply (UPS)
- TV Power
- A dapter/Charger



Key Performance Parameters

Parameter	Value	Unit
V_{DS}	650	V
R _{DS(on),typ}	2.7	Ω
$Q_{g,typ}$	12.6	nC
I _D	4	Α
I _{D,pulse}	16	Α

Device Marking and Package Information

Device	Package	Marking
DD65N04AFT	TO-220F	65N04AFT
DD65N04AD	TO-252	65N04AD

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Absolute Maximum Ratings $T_C = 25^{\circ}C$, unless otherwise noted				
Parameter		Symbol	Value	Unit
Drain-Source Voltage(V _{GS} =0V))	V _{DS}	650	V
Continuous Drain Current¹)	T _C = 25°C		4	^
Continuous Drain Current	T _C = 100°C	I _D	2.4	A
Pulsed Drain Current ²⁾	•	I _{D,pulse}	16	А
Gate-Source Voltage		V_{GS}	±30	V
Single Pulse Avalanche Energy³)		E _{AS}	208	mJ
Peak Diode Recovery dv/dt 4)		dv/dt	5	V/ns
Power Dissipation For TO-220F		В	26.7	10/
Power Dissipation For TO-252		P _D	34.4	W
Continuous Diode Forward Current		Is	4	
Diode Pulsed Current ²⁾		I _{S,pulse}	16	A
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55~+150	°C

Thermal Resistance For TO-220F			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R_{thJC}	4.69	• °C/W
Thermal Resistance, Junction-to-Ambient	R_{thJA}	80	*C/VV

Thermal Resistance For TO-252			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R_{thJC}	3.63	°C/W
Thermal Resistance, Junction-to-Ambient	R_{thJA}	62	0/ ۷۷

Notes

- 1) Limited by maximum junction temperature.
- 2) Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3) L=26mH, I $_{AS}$ =4A, RG=25 Ω ,VDD=80V,Start TJ=25 $^{\circ}$ C.
- 4) $I_{SD} \le 4A$, di/dt $\le 100A/\mu s$, VDD $\le BV_{DSS}$, Start $T_J = 25$ °C.

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Downwater		To at Oour distings		Value		
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0V, I_D = 250\mu A$	650			V
Zero Gate Voltage Drain Current		$V_{DS} = 650V$ $V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	шΛ
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 650V,$ $V_{GS} = 0V, T_{J} = 150^{\circ}C$			100	μΑ
Gate-Source Leakage Current	I _{GSS}	$V_{GS} = \pm 30V$			±100	nA
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2		4	V
Drain-Source On-State-Resistance	R _{DS(on)}	$V_{GS} = 10V, I_D = 2A$		2.7	3.1	Ω
Gate Resistance	R _G	f = 1.0MHz open drain		1.4		Ω
Dynamic Characteristics						
Input Capacitance	C _{iss}			537		pF
Output Capacitance	C _{oss}	$V_{GS} = 0V, V_{DS} = 25V$ f = 1.0MHz		42		
Reverse Transfer Capacitance	C _{rss}			1.3		
Total Gate Charge	Qg			12.6		
Gate-Source Charge	Q_{gs}	$V_{DD} = 520V, I_{D} = 4A$		4.2		nC
Gate-Drain Charge	Q_{gd}	$V_{DD} = 520V, I_{D} = 4A$ $V_{GS} = 10V$		2.6		
Gate Plateau Voltage	V _{Plateau}			4.9		V
Turn-on Delay Time	t _{d(on)}	$V_{DD} = 325V, I_{D} = 4A$ $R_{G} = 12\Omega, V_{GS} = 10V$		14		
Turn-on Rise Time	t _r			16		
Turn-off Delay Time	t _{d(off)}			32		ns
Turn-off Fall Time	t _f			11		
Drain-Source Body Diode Character	ristics		•		· · · · ·	
Body Diode Forward Voltage	V _{SD}	$T_J = 25^{\circ}C, I_{SD} = 4A$ $V_{GS} = 0V$			1.2	V
Reverse Recovery Time	t _{rr}	V _R = 520V		256		ns
Reverse Recovery Charge	Q _{rr}	$I_F = 4A, di_F/dt = 100A/\mu s$		1.2		μC



Typical Characteristics $T_J = 25^{\circ}$ C, unless otherwise noted

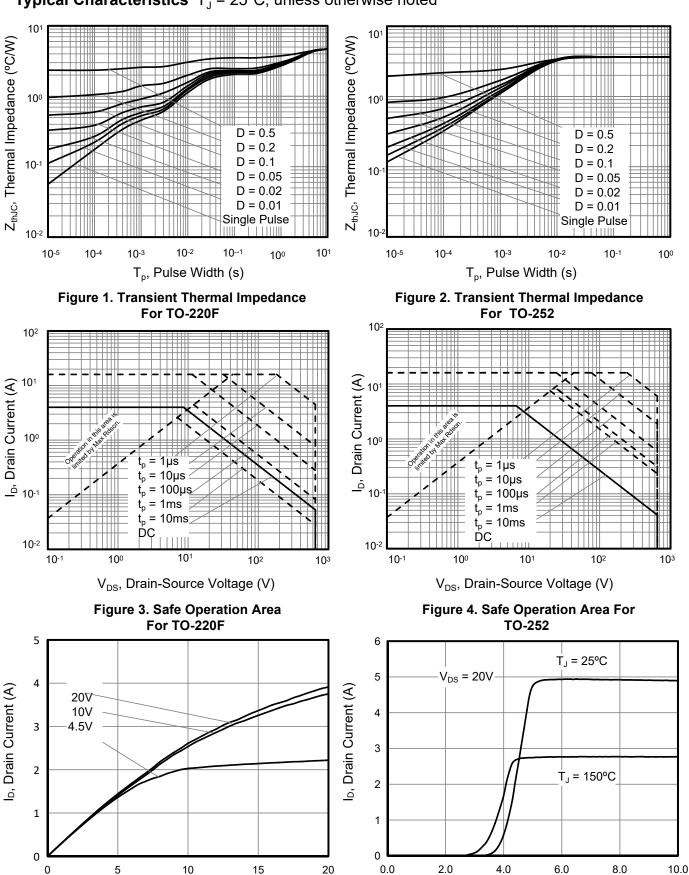


Figure 5. Output Characteristics

V_{DS}, Drain-to-Source Voltage (V)

Figure 6. Transfer Characteristics

V_{GS}, Gate-to-Source Voltage (V)



Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted

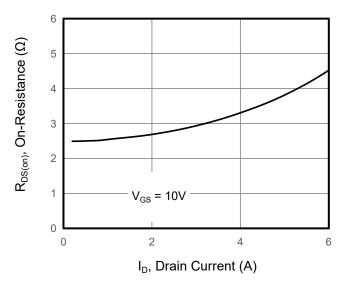
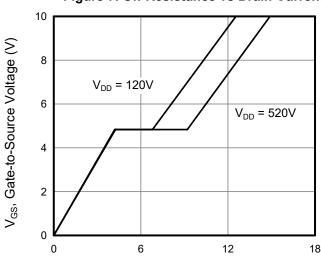


Figure 7. On-Resistance vs Drain Current



Q_g, Total Gate Charge (nC) Figure 9. Gate Charge

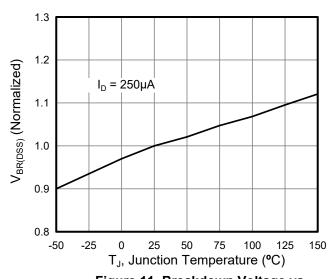


Figure 11. Breakdown Voltage vs Junction Temperature

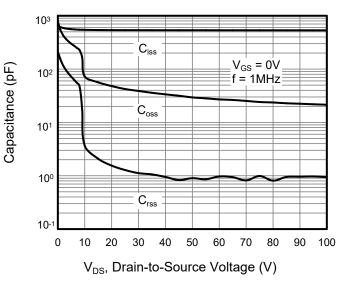


Figure 8. Capacitance

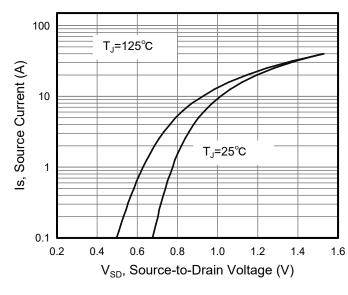


Figure 10. Body Diode Forward Voltage

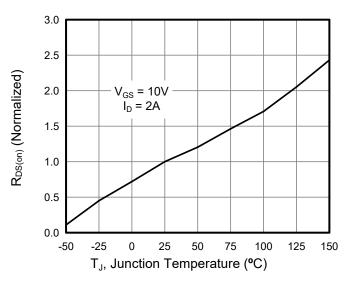


Figure 12. On-Resistance vs Temperature

Figure A: Gate Charge Test Circuit and Waveform

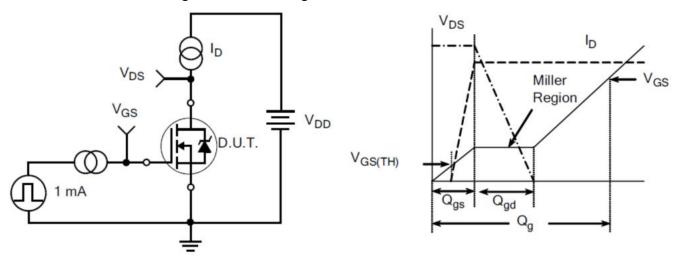


Figure B: Resistive Switching Test Circuit and Waveform

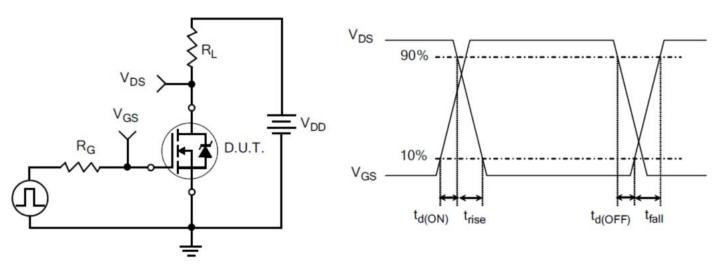
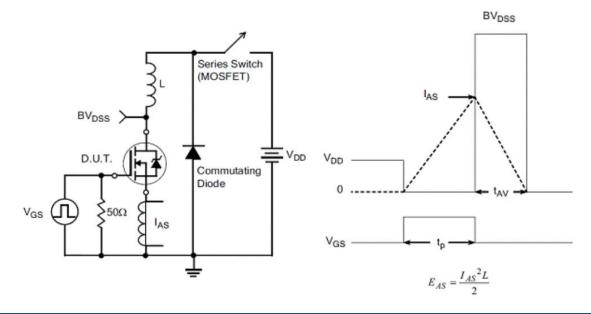
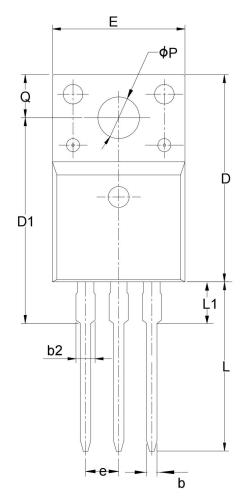


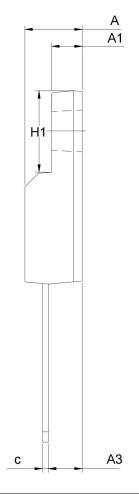
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





Outlines TO-220F Package

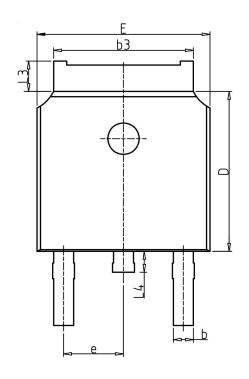


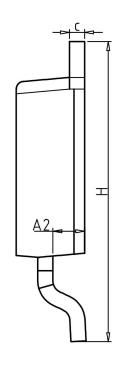


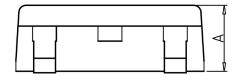
SYMBOL	Unit: mm		
STWIBOL	MIN	MAX	
А	4.45	4.9	
A1	2.3	2.8	
A3	2.5	3.03	
b	0.65	0.95	
b2	1.28	1.56	
С	0.4	0.65	
D	15.5	16.24	
D1	15.27	16.07	
E	9.91	10.36	
е	2.54BSC		
H1	6.48	6.88	
L	12.5	13.6	
L1	2.6	3.5	
ФР	3.03	3.48	
Q	3.1	3.5	

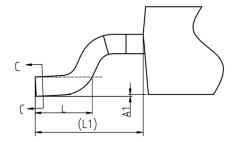


Outlines TO-252 Package









SYMBOL	Unit: mm		
STWIBOL	MIN	MAX	
Α	2.1	2.5	
A1	0	0.2	
A2	0.88	1.17	
b	0.5	0.9	
b3	5.1	5.53	
С	0.4	0.62	
D	5.4	6.4	
E	6.3	6.9	
е	2.286BSC		
Н	9.25	10.5	
L	1.35	1.8	
L1	2.4	3.4	
L3	0.82	1.412	
L4	0.5	1	

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